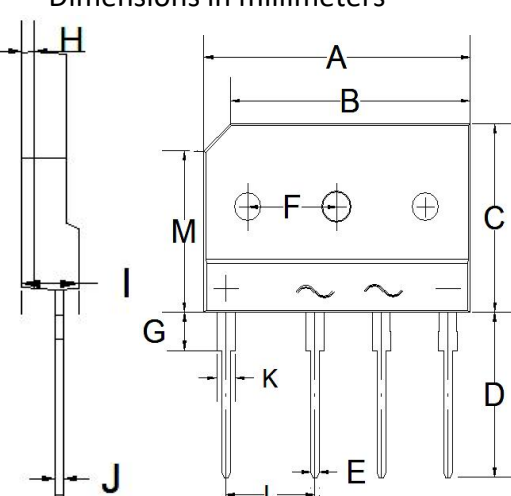


| 特征/Features | 外形尺寸/Outline Dimensions | | | | | |
|--|--|------|--|-------|---------|---------|
| <ul style="list-style-type: none"> ◆ GPP芯片 Glass passivated chip ◆ 低反向漏电流 Low Reverse Leakage Current ◆ 高耐浪涌电流能力 High surge current capability ◆ 接线端与壳体间绝缘耐压2500V Case to Terminal Isolation Voltage 2500V | Case: GBJ Series Dimensions in millimeters | | | 序号 | Min(mm) | MAX(mm) |
| |  | | | A | 29.8 | 30.2 |
| B | | | | 24.68 | 28.68 | |
| C | | | | 19.8 | 20.2 | |
| D | | | | 17.4 | 17.8 | |
| E | | | | 0.95 | 1.05 | |
| F | | | | 9.8 | 10.2 | |
| G | | | | 3.9 | 4.2 | |
| H | | | | 0.85 | 1.3 | |
| I | | | | 4.4 | 4.8 | |
| J | | | | 0.5 | 0.8 | |
| K | | | | 1.8 | 2.4 | |
| L | 9.8 | 10.2 | | | | |
| M | 16.4 | 17.0 | | | | |

机械参数/Mechanical Data

- ◆ 本体：塑封
Case: plastic package
- ◆ 标识/极性：本体标记
Marking / Polarity: Marked on Body
- ◆ 重量：约克
Weight: About 6.9grams

极限值/Maximum Ratings and Thermal Characteristics @ Ta = 25°C unless otherwise noted

| 符号 Symbol | 特性 Characteristic | GBJ8 | | | | | | | 单位 Unit |
|-----------------------------------|---|----------|-----|-----|-----|-----|-----|------|------------------|
| | | 005 | 01 | 02 | 04 | 06 | 08 | 10 | |
| V _{RRM} | 最大反向重复峰值电压 Maxmum Recurrent Peak Reverse Voltage | 50 | 100 | 200 | 400 | 600 | 800 | 1000 | V |
| I _{F(AV)} | 平均整流输出电流 Average Forward Output Rectified Current@Ta=120°C | 8 | | | | | | | A |
| V _F | 正向峰值电压 Forward Voltage Per Leg @I _{FM} =8.0A | 1.0 | | | | | | | V |
| I _{FSM} | 正向浪涌电流 Peak Forward Surge Current 8.3ms Single Half Sine-wave superimposed on rated load | 250 | | | | | | | A |
| I _R | 反向漏电流 Maximum DC reverse current at rated DC blocking voltage per leg | 5 500 | | | | | | | uA |
| i ² t | 热容值 Rating for fusing (t<8.3ms) | 260 | | | | | | | A ² S |
| V _{isol} | 绝缘耐压 Rms isolation voltage from case to leads | 2500 | | | | | | | V |
| C _J | 典型结电容 Typical Junction Capacitance | 50 | | | | | | | pF |
| R _{θJC} | 热阻 Maximum thermal resistance per leg | 2.0 | | | | | | | °C/W |
| T _j , T _{STG} | 结温，存储条件 Operating Junction and storage temperature range | -55~150 | | | | | | | °C |

Note:

- (1) Junction to case with heatsink
- (2) Recommended mounting position is to bolt down on heatsink with silicone thermal compound for maximum heat transfer with M3 screw .

◆ 特性曲线 (典型) Characteristics(Typical)

Fig 1-forwardCurrent derating Curve
图1正向电流降额曲线

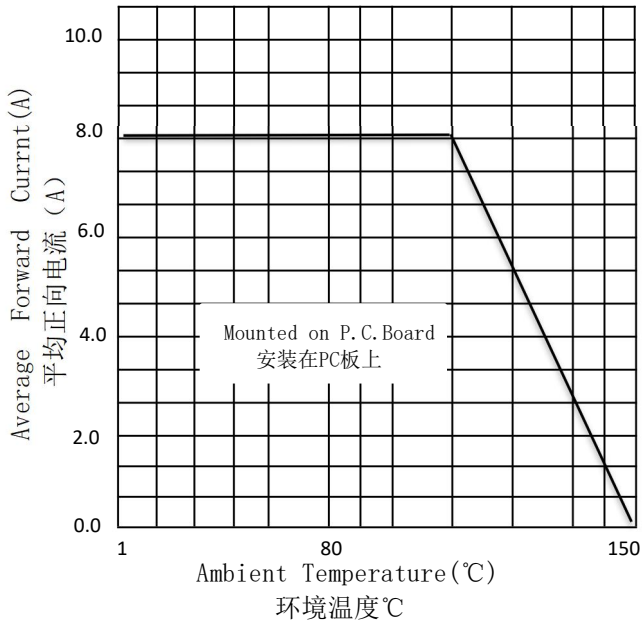


Fig. 2-Maximum Non-Repetitive Surge Current
图2 最大不重复正向浪涌曲线

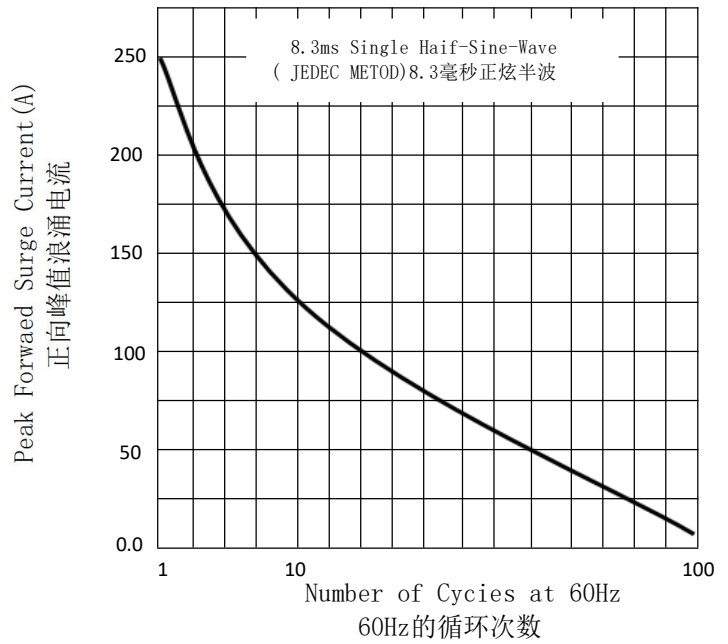


Fig. 3-Typical Reverse Characteristics
图3. 典型的反向特性

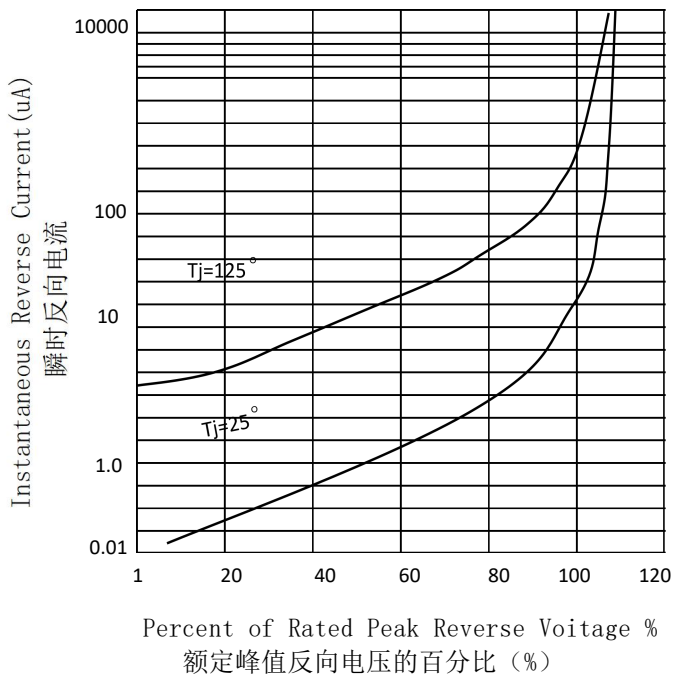


Fig. 4-Typical Forward Characteristics
图4. 典型的正向特性

